Silica     7631-86-9     Lead Frame     0.242     0.449     2,419     Phthalcyanne Blue, Organic Planc       Nickel     7440-02-0     Lead Frame     0.093     0.172     929       Aromatic Carbonyl Compound     7727-43-7     Lead Frame     0.093     0.172     929       Arine Compound     14607-96-6     Lead Frame     0.015     0.028     151       Levelling Agents & Others     25068-38-6     Lead Frame     0.031     0.633     3,413       Dipropylene Glycol Monomethyl Ether     34590-94-8     Lead Frame     0.051     0.086     5,314       Artlig Boiling Point Petroleum Solvent     9003-36-5     Lead Frame     0.091     0.168     907       Acrylic Monometry     7631-86-9     Lead Frame     0.047     0.272     1.469     0.147     9.023     4.990       Organic Filler     7727-43-7     Lead Frame     0.050     0.092     4.970     4.970     4.970     4.970     4.970     4.970     4.970     4.970     4.970     4.970     4.970     4.970     4.970     4.970 <td< th=""><th colspan="3">n Base Alloy: Package Homogeneous Materials: Alloy (Cu) 8.1 Electronics (e.g. pc boards, displays)</th></td<>	n Base Alloy: Package Homogeneous Materials: Alloy (Cu) 8.1 Electronics (e.g. pc boards, displays)		
Basic Subtance     CAS Number     Sub-Component     Weight     mg/pn     pnm     195.55     (mg) Total     195.55 </th <th></th> <th></th> <th>e8</th>			e8
Siles, views.     0007940-0     Mold Compound     0.728     9.729     0.778.3     9.729     0.778.3     9.729     0.778.3     9.729     0.778.3     9.729     0.778.3     9.729     0.778.3     0.778.3     0.778.3     0.778.3     0.778.3     0.778.3     0.757 <th0.757< th="">     0.757     0.75</th0.757<>	Mold Compound	d % ot Total Weig	ht 56.90
Epop Ream     Trade Secter     Mold Compound     2.88     6.000     92.831       Product Ream     Table Secter     Mold Compound     2.888     6.000     92.831       Copper     7446-554     Lead Frame     0.590     1.783     95.04       Compart Mark     80.05     1.783     1.583     6.000     92.01       Compart Mark     90.05     1.783     1.583     6.000     92.01       Compart Mark     90.05     1.481     1.481     6.000     92.01     90.000     0.177     90.000     90.000     90.000     90.000	us 60676-86-0	89.25	
Phenologic Ream     Trads Scort     Mold Compound     Z 48     4.962     4.967     Control lists       Prohibitystem Sils, Organic Right     133.964 - Mold Compound     0.146     0.127     6.73     Cancon lists       Prohibitystem Sils, Organic Right     69997-173     Lists Frame     0.242     0.449     7.41     Prohibitystem Sils, Organic Right		5.77	-
Opport     7440-05-0     Lead Frame     0.500     1763     0.504     4.07     (mg) Test       Comparing Blue, Organic Planeth (Septer 14, 200)     0.632     0.122     6.52     0.449     2.419       Annuals, Carlson (Comparing Annuals, Carlson (Comparing 1, 200)     1.638     1.637     1.638     0.128     0.53     0.149     2.421     0.449     2.419     0.449     2.419     0.449     2.419     0.449     2.419     0.449     2.419     0.449     2.419     0.449     2.419     0.449     2.419     0.449     2.419     0.449     2.419     0.449     2.419     0.449     2.419     0.449     2.419     0.449     2.419     0.411     0.53     0.51     0.53     0.51     0.53     0.51     0.53     0.51     0.55     0.50     <		4.72	
Phyladjagane Bio. Oppin: Pigment     6699     rmp. Test       Milledingie. playment     0406     0.005     0.005     0.005     0.007     0.00	ck 1333-86-4	0.26	
cmaldalyda, palymer with 2 (chronnethylicotare and phenol 90330-5.     Lead Frame     0.486     0.902     4.860       Aronasic Cartsony Compound     7727-43-7     Lead Frame     0.053     0.172     450       Aronasic Cartsony Compound     7727-43-7     Lead Frame     0.015     0.028     151       Duropene Orgen Montenenthylicotare and phenol 900330-85     Lead Frame     0.015     0.028     151       Marine Compound     7727-43-7     Lead Frame     0.051     0.058     0.016       Marine Compound     4407-66.     Lead Frame     0.051     0.188     0.016     0.028     0.016     0.028     0.016     0.026	Тс	Total 100.	00
maldebyds, polymer with 2 (chromethylociners and phenol     9003-86     Lead Frame     0.466     0.902     4.860       Aromaic Cartoxyl Computed     7777-47-7     Lead Frame     0.033     0.172     4600       Annie Computed     7777-47-7     Lead Frame     0.015     0.028     6.131       Duppers Oper Monomethylociners and phenol     2450-944     Lead Frame     0.015     0.028     6.131       Marcia Cartoxyl Computed     2450-944     Lead Frame     0.015     0.028     6.314       Hogh Boling Post Reser     7440-20     Lead Frame     0.619     0.026     4.007       Commune     9603-944     Lead Frame     0.619     0.026     4.007       Commune     9404     Lead Frame     1.616     2.997     1.617       Commune     9406     Lead Frame     1.616     2.997     1.617       Commune     9404     Lead Frame     1.616     2.997     1.617       Commune     7440-273     Lead Frame     1.616     2.997     1.617       Commune     7440-273     Lead Fram	Lead Frame	% of Total Weig	ht 21.60
Sitic     761146-0     Lead Frame     0.242     0.446     2.419       Amme Compond     14402.0-1     Lead Frame     0.031     0.046     2.410       Amme Compond     14402.0-1     Lead Frame     0.016     0.026     161       Lowelling Apents A Chara     0.000     0.112     0.000     112     0.000       Bit Department Control     0.001     0.016     0.002     4.017       Amme Compond     761146-0     Lead Frame     0.001     0.016     0.002     4.017       Hib Delling     77274.37     Lead Frame     0.017     0.022     4.016     Daropster Elling     77274.37       Continuos Filamet Fiber Glass     14407.956     Lead Frame     1.511     0.002     4.017       Exox Finan     0.030     0.646     3.000     0.002     4.017       Continuos Filamet Fiber Glass     14407.957     Lead Frame     1.511     0.026     4.027       Bittom Gram     7440.575     Lead Frame     0.030     0.066     3.020       Strom     7440.575     L	Copper 7440-50-8	4.40	
Aromalic Castropord     777.4-7.7     Lead Frame     0.035     0.17     0.93       Amma Compandi     44807.66.1     Lasd Frame     0.031     0.033     3.413       Build Castrophic Signal Momenting Eter     3490.04.5     Lasd Frame     0.031     0.033     3.413       Build Data     100.012     0.027     0.041     0.033     4.040       Comma Campanding     100.027     0.041     0.033     4.040     1.017     0.011		0.03	
Anne Compound     1480796-6     Lead Frame     0.015     0.028     151       Developing Agains & Others nor     2008-364     Lead Frame     0.031     0.089     5.314       Developing Frame     0.081     0.089     5.314     Down	r with 2- 9003-36-5	2.25	
Leveling Agent & Others     2008-38-8     Lead Frame     0.480     0.112     605       Discoption Spect Monomity Effer     3468-44-3     Leas Frame     0.481     0.683     547       Hind Boling Paint Protoken Selvent     903-35-3     Leas Frame     0.491     0.583     547       Hind Boling Paint Protoken Selvent     703-58-9     Leas Frame     0.492     0.227     4.462       Common Selvent Frame     740-025     Leas Frame     0.493     0.726     4.469       Micro Selvent Frame     7460-25-1     Leas Frame     7.616     2.997     16.157       Binnalemide     2669-36-4     Leas Frame     7.616     2.997     16.157       Common Selvent Frame     6.131     1.337     15.344     1.337     15.344       Meder     7440-25-3     Leas Frame     0.130     0.252     1.501       Binnalemide     7440-25-3     Leas Frame     0.130     0.252     1.501       Binnalemide     7440-25-3     Leas Frame     0.130     0.254     1.500       Binnalemide     7440-25-3	Silica 7631-86-9	1.12	
Decogram     Operation     Odd     Odd     Odd     Odd     Odd     Odd     Odd     Operation	Nickel 7440-02-0	1.12	
3. Methow-3-Methol Bayl-Actetate     system     Least Frame     0.531     0.986     5.314     Dyspective Bayl Bayl Actetate       Mith Boling Porth Ferticisans Solvert     9033.855     Least Frame     0.469     0.535     6.977       Copy Relin     7454.02-0     Least Frame     0.469     0.526     4.987       Continuous Flament Flor Class     14807.96-6     Least Frame     0.616     2.997     1.849     6.937     1.999     6.933     1.999     0.936     4.997     1.999     6.937     1.999     6.937     1.999     6.937     1.999     6.937     1.999     6.937     1.999     6.937     1.999     6.937     1.999     6.937     1.999     6.937     1.999     6.937     1.999     6.937     1.999     6.937     1.999     6.937     1.999	mpound 7727-43-7	0.43	_
High Balling Point Perturbation Solvent     903:38-5     Lead Frame     0.091     0.168     007       Margiel Monome     773:16-6     Lead Frame     0.467     0.272     1.469       Epoxy Netain     779:02-0     Lead Frame     0.469     0.255     4.169       Continuous Flamment Flame Claime     1.616     2.907     16.157     Fig		0.07	_
Acysis     Meanmem     1031-86-9     Lase Frame     0.147     0.272     1.489       Expox/Resm     7464/20-1     Lase Frame     0.469     0.269     4.990       Continuous Flammel Ther Glass     1746/796-6     Lase Frame     0.161     2.297     161.67       Trazin     3400-94-8     Lase Frame     1.616     2.297     161.67       Depoy fram     3200-276     Lase Frame     1.616     2.297     161.67       Depoy fram     3200-276     Lase Frame     1.616     2.297     161.67       Depoy fram     3200-276     Lase Frame     0.134     11.379     0.134       Model     7440-276     Lase Frame     0.130     0.255     3.207       Silicon     7440-273     Dia Allach     0.030     0.256     3.027       Silicon     7440-274     Wite Bood Copper palladum coded (LaPAu)     0.33     0.455     3.427       Opger     7440-274     Wite Bood Copper palladum coded (LaPAu)     0.34     0.500     0.001     4       Copper     7440-274 <t< td=""><td></td><td>0.28</td><td></td></t<>		0.28	
Epony Resin     1440/020     Lead Frame     0.489     0.282     4.990     4.990       Organic Filer     7727.437     Lead Frame     0.056     0.002     4.970       Continuous Filarent Fiber Glass     14407.956     Lead Frame     3.810     7.058     38.107       Brownen     9490.949     Lead Frame     3.052     5.559     30.024       Epony Resin     9490.949     Lead Frame     5.161     2.755     15.012     2.755		1.58	
Organic Filer     772743-7     Lead Frame     0.050     0.092     497       Billion Filer     20050-36     Lead Frame     1.810     7.206     38.10     7.207       Billion Filer     20050-36     Lead Frame     1.810     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.10     7.206     38.11     47.50     0.821     47.50     0.83     47.50     0.83     47.50     0.83     48.11     47.50     0.83     47.50     0.83     47.50     0.83     47.50     0.83     48.11     47.50     0.83     47.50     0.83     47.50     8.81     47.50     8.81     47.50     8.81     47.50     8.81     47.500     8.81     47.50     8.81 <t< td=""><td></td><td>0.42</td><td>-1</td></t<>		0.42	-1
Continuous Filamma Fiber Glass     1480736-6     Lead Frame     3.810     7.058     38.102       Binmalemide     2668.386     Lead Frame     1.616     2.607     16.167     2.007     16.167     2.007     16.167     2.007     16.167     2.007     16.167     2.007     16.167     2.007     16.167     2.007     16.167     2.007     16.167     2.007     16.167     2.007     16.167     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     16.161     2.007     16.161     2.007     16.161     2.007     16.161     2.007     16.161     16.000     16.000     16.000     16.000     16.000     16.000     16.000     16.000     16.000     16.000     16.000     16.000     16.		0.42	
Bismaleminic     25068-38-6     Lead Frame     1.616     2.997     16,157       Triazine     34500-34-8     Lead Frame     1.616     2.997     16,157       Dismaleminic     24607-6     Lead Frame     1.013     0.157     0.568     30,024       Organ     1.113     1.157     0.157     0.158     0.252     1.361       Organ     24607-55     Lead Frame     0.138     0.252     1.361     0.056     30.00       Silver     7440-22-4     Die Attach     0.505     0.648     3.600     0.00     0.056     30.00     0.001     4.000     0.003     0.056     30.00     0.001     4.000     0.001     4.000     0.001     4.000     0.001     4.000     0.001     4.000     0.001     4.000     0.001     4.000     0.000     0.001     4.000     0.000     0.001     4.000     0.000     0.001     4.000     0.000     0.001     4.000     0.000     0.001     4.000     0.000     0.000     0.000     0.000     0	y Resin 7440-02-0	2.31	-1
Traizine   34690-94-8   Lead Frame   1.616   2.907   16,157     Epoxy Resin   2462: 77.6   Lead Frame   3.002   5.569   3.002     Nickal   7440-027.6   Lead Frame   1.031   2.785   16,012     Odd   7440-027.6   Lead Frame   0.038   0.022   15.014     Gold   7440-027.6   Lead Frame   0.039   0.056   3.02     Silver   7440-027.6   Lead Frame   0.030   0.056   3.02     Silver   7440-027.3   Die Atlach   0.120   0.223   1.000     Coppor   7440-05.6   Wire Bord Coppor pallatium coater (CuP4Au)   0.001   0.013   7.00     Coppor   7440-05.6   Wire Bord Coppor pallatium coater (CuP4Au)   0.000   0.011   4.000   56.61   5.00<		0.23	-
Epoxy Resin     System     Lead Frame     3.002     5.669     30.024       Inorganic fille     24625.776     Lead Frame     1.501     2.785     15.124       Copper     7440.575     Lead Frame     6.134     11.379     61.344       Nickal     7440.575     Lead Frame     6.134     0.235     0.649     3.500       Silve     7440.524     Dis Atlach     0.326     0.586     3.000       Epoxy Resin     Trade secret     Die Atlach     0.030     0.656     3.000       Silven     7440.56-8     Wire Bord Copper palladium coated (CuPGAu)     0.434     0.636     3.427     Silver       Pallodum     7440.51-5     Wire Bord Copper palladium coated (CuPGAu)     0.434     0.636     3.427     Silver       Silver     7440.51-5     Wire Bord Copper palladium coated (CuPGAu)     0.434     0.636     1.000, 000     10.652     2.062     156.615     Silver       Silver     7440.50-8     Wire Bord Copper palladium coated (CuPGAu)     0.434     1.000, 000     1.000, 000     1.000, 000     1.000, 000 <td></td> <td>17.64</td> <td>-</td>		17.64	-
Inorganic filler   24623-77-6   Lead Frame   1.501   2.785   15.012     Copper   744057-5   Lead Frame   6.134   11.370   6.1344     Nickel   744052-0   Leas Frame   0.136   0.252   1.381     Solor   744057-1   Los Frame   0.136   0.252   1.381     Solor   744027-3   Die Attach   0.130   0.223   1.200     Epoxy Resin   Trade secret   Die Attach   0.030   0.056   300	aleimide 25068-38-6	7.48	-
Copper     7440-57-5     Lead Frame     6.134     11.377     61.344     Filt Stress       Gold     7440-57-5     Lead Frame     0.030     0.056     302       Silver     7440-57-5     Lead Frame     0.030     0.056     302       Binom     7440-21-3     Die Attach     0.130     2.056     7.000       Silver     7440-57-5     Lead Frame     0.030     0.056     302       Binom     7440-57-5     Lead Frame     0.130     2.056     7.000       Silver     7440-50-8     Wire Bord Copper plandsum coated (CuP4Au)     0.007     0.013     4.831     4.77.600     8.811     6.8.1     (mg) Total     Epoxy Rest       Odd     7440-50-8     Wire Bord Copper plandsum coated (CuP4Au)     0.000     0.011     7.00     Silver     False Silver     Epoxy Rest       Silver     7440-50-8     Plainig on external leads (pins) (SAC105)     0.168     0.48     (mg) Total     Epoxy Rest       Octpoper     7440-50-8     Plainig on external leads (pins) (SAC105)     0.080     0.477     Fo	Triazine 34590-94-8	7.48	-
Nickel   7440-02-0   Lead Frame   0.138   0.252   1.361     Gold   7440-57-5   Lead Frame   0.030   0.056   300     Silver   7440-52-4   Die Attach   0.250   1.200   1.200     Epory Resin   Trade secret   Die Attach   0.120   0.223   1.200     Silvon   7440-21-3   Die Attach   0.120   0.223   1.200     Copper   7440-21-3   Wire Boot Copper patiadum coated (CuP4Au)   0.030   0.046   3.047   Silver     Gold   7440-25-4   Wire Boot Copper patiadum coated (CuP4Au)   0.030   0.011   4.750   0.93   (mg) Total     Silver   7440-25-4   Plaing on external leads (pins) (SAC105)   15.602   2.90.62   156.615   5     Silver   7440-25-4   Plaing on external leads (pins) (SAC105)   0.030   1.000.000   1.000   1.000   0.65   (mg) Total     Copper   7440-50-8   Plaing on external leads (pins) (SAC105)   0.030   1.000,000   0.055   (mg) Total     Microchiy Technology   Notestage   Notestage   Notestage   Notestage	y Resin system	13.90	
Gold     7440-57-5     Lead Frame     0.030     0.056     302       Silver     7440-224     Die Attach     0.120     0.223     1.200       Epory Rein     7440-21-3     Die Attach     0.120     0.223     1.200       Silver     7440-21-3     Die Attach     0.030     0.056     3.007       Gold     7440-21-3     Wire Boot Coper Pailadum coated (CuPAu)     0.007     0.011     4.150       Gold     7440-27-5     Wire Boot Coper Pailadum coated (CuPAu)     0.000     1.001     4.150       Gold     7440-57-5     Wire Boot Coper Pailadum coated (CuPAu)     0.000     1.001     4.150       Silver     7440-27-4     Plaing on external leads (pins) (SAC105)     0.159     0.295     1.590     8.81     (mg) Teal       Silver     7440-50-8     Plaing on external leads (pins) (SAC105)     0.169     0.295     1.000.000     1.000.000     1.000.000     1.000.000     1.000.000     1.000.000     1.000.000     1.000.000     1.000.000     1.000.000     1.000.000     1.000.000     1.000.000     1.000.000	nic filler 24623-77-6	6.95	
Silver   7440-224   Die Attach   0.350   0.649   3.500     Epoxy Resin   Trade secret   Die Attach   0.120   0.223   1.200     Siltion   7440-50-8   Wire Bond Copper pailadum costed (2uP4u)   0.030   0.056   3.000     Pailadum   7440-50-8   Wire Bond Copper pailadum costed (2uP4u)   0.043   0.656   3.427   Silton     Ord   7440-50-8   Wire Bond Copper pailadum costed (2uP4u)   0.050   0.562   3.000   Silton   Silton     Ord   7440-50-8   Wire Bond Copper pailadum costed (2uP4u)   0.000   165.62   0.062   15.615   Silton   Epoxy Resin   Teleping on stemail leads (pins) (SAC105)   0.128   1.000,000   1.000,000   1.000,000   1.000,000   1.000,000   1.000,000   0.65   (mg) Total   Died Silton   D	Copper 7440-57-5	28.40	
Epoxy Resin     Trade servet     Die Atlanh     0.030     0.056     300       Silicon     7440-50-8     Wire Bond Copper palladium coated (CuP4Au)     0.343     0.636     3.427       Palladium     7440-50-8     Wire Bond Copper palladium coated (CuP4Au)     0.007     0.001     4       Gold     7440-57-5     Wire Bond Copper palladium coated (CuP4Au)     0.000     0.001     4     Silver     Silver     Silver     7440-22-4     Plating on external leads (pins) (SAC105)     1.5662     2.902     156.615     Expory Resi       Copper     7440-22-4     Plating on external leads (pins) (SAC105)     0.080     1.000,000     1.500     8.81     (mg) Total       Docode     0.1855 g     Total Mass     0.65     (mg) Total     Docode	Nickel 7440-02-0	0.63	
Image: Silver   7440-21-3   Chip (Die)   4.750   8.811   47.500   0.93   (mg) Total     Palladium   7440-50-8   Wire Bond Copper palladium coated (CuP4Au)   0.007   0.013   70   Silver     Reg   Tin   7440-57-5   Wire Bond Copper palladium coated (CuP4Au)   0.000   0.001   4   Silver   Silver   7440-22-4   Plating on external leads (pins) (SAC105)   1.562   2.90.52   156.615   Copper   70   Export Resi   Silver   7440-22-4   Plating on external leads (pins) (SAC105)   0.080   0.417   795   Deped Silce   Deped Silce   Deped Silce   Deped Silce   Deped Silce   Deped Silce   Copper   7440-22-4   Plating on external leads (pins) (SAC105)   0.080   1.080,000   1.080	Gold 7440-57-5	0.14	
Copper     7440.06-8     Wire Bond Copper palladum coated (CuP4Au)     0.343     0.636     3.427     Silver       Gold     7440.06-3     Wire Bond Copper palladum coated (CuP4Au)     0.007     0.013     70     Silver       Tin     7440.05-5     Wire Bond Copper palladum coated (CuP4Au)     0.000     0.001     4     Epox Real       Silver     7440.25-4     Wire Bond Copper palladum coated (CuP4Au)     0.000     0.0147     735       Copper     7440.25-4     Plating on external leads (pins) (SAC105)     0.189     0.147     795       Copper     7440.25-8     Total Mass     TotALS:     100.000     1.85.500     1.000,000       O.1855 g Total Mass     0.185 f Total Mass     0.65     (mg) Total       miconductor device and its homogenous material substance is 00295/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2006/3/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero)     0.85     (mg) Total       ance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.     Image: antional ingredient in the semiconductor device and, to the best of Microchip Technology incorporatet anotical substance, if anotibe document, there is no	Тс	Total 100.	00
Paladium   7440-55-3   Wire Bond Copper paladium coated (CuP4xu)   0.007   0.013   70     Gold   7440-57-5   Wire Bond Copper paladium coated (CuP4xu)   0.000   0.001   4     Tin   7440-57-5   Plating on external leads (pins) (SAC105)   15.662   29.052   1556.615     Silver   7440-22-4   Plating on external leads (pins) (SAC105)   0.080   0.147   795   205   1500   0.065   (mg) Total     O Copper   7440-50-8   Plating on external leads (pins) (SAC105)   0.080   0.147   795   205   500   1.000,000   0.655   (mg) Total     O Copper   7440-50-8   Plating on external leads (pins) (SAC105)   0.080   0.147   795   205   500   1.000,000   0.655   (mg) Total     O Copper   7440-50-8   Plating on external leads (pins) (SAC105)   0.080   0.147   795   205   500 <t< td=""><td>Die Attach</td><td>% of Total Weig</td><td>ht 0.50</td></t<>	Die Attach	% of Total Weig	ht 0.50
Paladium   7440-55-3   Wire Bond Copper paladium coated (CuP4xu)   0.007   0.013   70     Gold   7440-57-5   Wire Bond Copper paladium coated (CuP4xu)   0.000   0.001   4     Tin   7440-57-5   Plating on external leads (pins) (SAC105)   15.662   29.052   1556.615     Silver   7440-22-4   Plating on external leads (pins) (SAC105)   0.080   0.147   795   205   1500   0.065   (mg) Total     TOTALS: 100.000   185.500   1,000,000   0.655   (mg) Total     OLSES g Total Mass   O.665   (mg) Total     miconductor device and its homogenous materials compty with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/663/EU (31 March ind 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero)   0.65   (mg) Total     ance with the above, EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.   28.40   (mg) Total     Gold     Outpret/web and bind for pastics. You can access the UL iQTM family of databases to obtain a test report at Lul.com/plastics/   28.49   (mg) Total     Copper   28.49   (mg) Total <td>7440-22-4</td> <td>70.00</td> <td></td>	7440-22-4	70.00	
Gold   7440-57-5   Wire Bond Copper pailed um coated (GuP4Au)   0.000   0.001   4   EpoxyReai     In   7440-31-5   Plaining on external leads (pins) (SAC105)   0.156   29.052   156.015   0.156   15.6615   0.000   0.477   795   0.000   0.477   795   0.000   0.010   4   0.000   0.017   795   0.000   0.017   795   0.000   0.017   795   0.000   0.055   (mg) Total   0.055   0.055   0.055   0.055   (mg) Total   0.055   (	7440-21-3	24.00	
Silver     7440-32-4     Plating on external leads (pins) (SAC105)     0.159     0.295     1.590     8.81     (mg) Total       Copper     7440-50-8     Plating on external leads (pins) (SAC105)     0.00     0.147     795       DOLD     0.155 g     ToTALS:     100.000     185.500     1,000,000     0.655     (mg) Total       miconductor device and its homogenous materials comply with EU Directives:     2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March     Copper       miconductor device and its homogenous materials comply with EU Directives:     2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March     Copper       mical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology     Palladium       mical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology     Gold       compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at 1, ul.com/plastics/     23.49     (mg) Total       tective "tubes" in which the specific product is shipped are made from polyvinyl choride (PVC) plastic. "Window envelopes" used to hold the pack	n Trade secret	6.00	
Copper     7440-50-8     Plating on external leads (pins) (SAC105)     0.080     0.147     795     Doped Silice       0.1855 g Total Mass     TOTALS:     100.000     185.500     1,000,000     0.65     (mg) Total       0.2005%/EC and 2016/74/EU (End-of-Life Vehicles (ELV) without exemption (zero)     0.65     (mg) Total     Copper       ance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.     Copper     Paladium       mical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology rated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if not below the threshold of regulatory concern world-wide.     Goid       g compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at tail.com/plastics/     29.49     (mg) Total       uip Technology Incorporated believes the information in this form concerning substances restricted by ROHS in Microchip Technology Incorporated semiconductor devices ordiginal packing materials is true and correct to the best of the knowledge and beinf, as of the date isginificant toxic metals Safety Data Sheets provided by raw material suppliers.     Tin       toin is provided only as estimates of tho aver	Тс	Total 100.	00
TOTALS:     100.000     185.500     1,000,000       0.1855 g     Total Mass     0.65     (mg) Total       miconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March d 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero)     Copper       ance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.     Palladium       mical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology for the other of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if a compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at pulcom/plastics/     29.49     (mg) Total       uiccomplastics/     and correct to the best of its knowledge and belief, as of the data listed in this form. Microchip Technology Incorporated cannot guarantee the teress and accuracy of data in this form concerning substances restricted by RoHS in Microchip Technology Incorporated cannot guarantee theress and accuracy of data in this form concerning substances or the average weight of anticipated significant toxic metals components. These estimates do not arrage weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not transpliers.     Tin       tion is provided only	Chip (Die)	% of Total Weig	ht 4.75
0.1855 g Total Mass   0.65 (mg) Total     miconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March d'2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero)   Copper     ance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.   Pailadium     mical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology prated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if not below the threshold of regulatory concern for any regulatory scheme world-wide.   29.49 (mg) Total     g compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at quil.com/plastics/   29.49 (mg) Total     viation "regulatory concern for any regulatory concerning substances restricted by ROHS in Microchip Technology Incorporated cannot guarante the thereas and accuracy of data in this form beause it has been compiled based on the ranges provided by RMicrochip Technology Incorporated cannot guarante the thereas and accuracy of data in their disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers.   Tin     hip Technology Incorporated does not provide and based con the ranges provided in Microchip Technology Incorporated canot these parts and the average weight of anticip		100.00	
Copper miconductor device and its homogenous materials comply with EU Directives: (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March d 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) ance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. mical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology rated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if u.l.com/plastics/ g compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at u.l.com/plastics/ int "reels" may be made from PVC plastic. wind the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box tain "reels" may be made from PVC plastic. int formation in this form concerning substances restricted by RoHS in Microchip Technology Incorporated cannot guarantee the teness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. ir information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. ir information soften protected from disclosure as trade secrets and the average weight of anticipated significant toxic metals components. These estimates do not trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts. hip Technology Incorporated does not provide and its subsidiaries	Тс	Total 100.	00
and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero)   Copper     ance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.   Palladium     mical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology varied's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if not below the threshold of regulatory concern for any regulatory scheme world-wide.   Gold     g compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at 1, ul.com/plastics/   29.49   (mg) Total     the trees" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box   29.49   (mg) Total     tin "reels" may be made from PVC plastic.   Tin formation in this form concerning substances restricted by RoHS in Microchip Technology Incorporated semiconductor devices and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers.   Tin     trip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided by subcordic product is subsidiaries are contained within silicon devices (silicon IC) in the finished parts.   Silver     tip Tec	Wire Bond Copper palladium coated (CuPdAu)		ht 0.35
ance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. mical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology roted's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if not below the threshold of regulatory concern for any regulatory scheme world-wide. g compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at pul.com/plastics/ tective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box tain "reels" may be made from PVC plastic. mip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated cannot guarantee the teness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. trinformation is often protected from disclosure as trade secrets and some information may not have been provided by subcortract assemblers and raw material suppliers. trinformation is often protected from disclosure as trade secrets and some information areay not have been provided by subcortract assemblers and raw material suppliers. The trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts. mip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product is provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standar	7440-50-8	97.90	
mical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology   Gold     grand of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if not below the threshold of regulatory concern for any regulatory scheme world-wide.   Gold     g compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at quil.com/plastics/   29.49   (mg) Total     otective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box rtain "reels" may be made from PVC plastic.   29.49   (mg) Total     hip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated cannot guarantee the teness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. ation is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. this form because it has been compiled based on the ranges provided in flusted assemblers and raw material suppliers. ation is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not estimates do not e trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.   Silver </td <td></td> <td></td> <td>_</td>			_
prated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if   Gold     g compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at   ul.com/plastics/     vul.com/plastics/   29.49   (mg) Total     potential registrics/   29.49   (mg) Total     tain "reels" may be made from PVC plastic.   and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated semiconductor devices   orginal packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated semiconductor devices   Tin     reference   rinformation in this form concerning substances restricted by RoHS in Microchip Technology Incorporated cannot guarantee the teness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. er information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. et arce levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.   Silver     hip Technology Incorporated does not provide and the subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's ons, sales order acknowledgement, and invoices.   Silver <td>7440-05-3</td> <td>2.00</td> <td>_</td>	7440-05-3	2.00	_
uil.com/plastics/   29.49   (mg) Total     ottective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box   29.49   (mg) Total     tain "reels" may be made from PVC plastic.   29.49   (mg) Total     hip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the teness and accuracy of data in this form disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers.   Tin     trin is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.   Silver     nip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in Microchip's standard terms and conditions of sale. These are provided in Microchip's or sale acknowledgement, and invoices.   Silver     nip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or   Silver	7440-57-5	0.10	
rtain "reels" may be made from PVC plastic.   29.49   (mg) Total     hip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices   Image: Semiconductor devices     original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the teness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. ation is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. ation is provided only as estimates of the average weight of anticipated significant toxic metals components. These estimates do not e trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.   Tin     hip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in Microchip's standard terms and conditions of sale. These are provided in Microchip's one of eracknowledgement, and invoices.   Silver     hip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or   Silver	Тс	Total 100.	00
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ties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's Silver ions, sales order acknowledgement, and invoices.	7440-31-5	98.50	
	7440-22-4	1.00	
Certificate of Compliance for semiconductor products.	7440-50-8	0.50	
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had package interface above a too fraction particulate on the latest of the calculate ist of Long which can be round at			